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To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Sang-duk LEE, Jeong-hwan LEE,  
Chung-hyuk SHIN and Jung-ki KIM

Additional name(s) of conveying party(ies) attached? ☐ yes ☒ no

2. Name and address of receiving party(ies):

Name: SAMSUNG ELECTRONICS CO, LTD.

Street Address: 416, Maetan-dong, Paldal-ku

City: Suwon State: Kyungki-do

Country: Republic of Korea

Additional name(s) & address(es) attached? ☐ yes ☒ no

3. Nature of Conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Other \_\_\_\_\_

Execution Date(s): January 13, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is January 14, 1999.

A. Patent Application No(s).

09245123

B. Patent No(s).

Additional numbers attached? ☐ yes ☒ no

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: HOWREY & SIMON

Internal Address:

Street Address: Box No. 34  
1299 Pennsylvania Ave, N.W.

City: Washington State: D.C. Zip Code: 20004-2402

6. Total number of applications and patents involved

7. Total fee (37 C.F.R. § 3.41).....\$ 40.00

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8. Deposit Account Number: 08-3038

02/11/1999 INTEL 0000034 09245123

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Michael J. Bell  
Registration No. 39,604

Signature

Total number of pages including cover sheet, attachments and document 3

January 14, 1999  
Date

OMB NO. 0651-0011 (exp. 4/94)

Mail documents to be recorded with required cover sheet information to:  
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PATENT  
REEL: 9758 FRAME: 0250

## ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to the undersigned: Sang-duk LEE, Jeong-hwan LEE, Chung-hyuk SHIN and Jung-ki KIM, the undersigned hereby sell and assign to SAMSUNG ELECTRONICS CO., LTD. (the Assignee), their entire right, title and interest

*check applicable box(es)*

☒: for the United States of America  
(as defined in 35 U.S.C. § 100),  
☒: and throughout the world,

in the invention known as Backlight Assembly for Use of Liquid Crystal Display Module, for which application for patent in the United States of America has been executed by the undersigned on \_\_\_\_\_ (also known as United States Application No. \_\_\_\_\_, filed \_\_\_\_\_), in any and all applications thereon, in any and all Letters Patent(s) therefor, and in any and all reissues, extensions, renewals, reexaminations of such applications or Letters Patent(s) and divisional and continuation applications thereof, to the full end of the term or terms for which such Letters Patent(s) issue, including all claims, if any, that may have arisen for infringement prior to the date of this assignment, such entire right, title and interest to be held and enjoyed by the above-named Assignee to the same extent as they would have been held and enjoyed by the undersigned had this assignment and sale not been made.

The undersigned agree to execute all papers necessary in connection with the application and any continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree to execute all papers necessary in connection with any interference that may be declared concerning the application or any continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned hereby represent that the undersigned has full right to convey the entire interest herein assigned, and that the undersigned has not executed, and will not execute, any agreement in conflict therewith.

The undersigned hereby grants:

Jeffrey I. Auerbach, Reg. No. 32,680  
Melvin L. Barnes, Jr. Reg. No. 38,375

Leslie L. Jacobs, Jr., Reg. No. 40,659  
Richard H. Kjeldgaard, Reg. No. 30,186

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of HOWREY & SIMON, BOX NO. 34, 1299 PENNSYLVANIA AVENUE, N.W., Washington, D.C. 20004-2402, power to insert in this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned on the date opposite their names.

Date: <u>January</u> , <u>13</u> , 1999	Signature of Inventor: <u>Sang-duk LEE</u> Sang-duk LEE
Date: <u>January</u> , <u>13</u> , 1999	Signature of Inventor: <u>Jeong-hwan LEE</u> Jeong-hwan LEE
Date: <u>January</u> , <u>13</u> , 1999	Signature of Inventor: <u>Chung-hyuk SHIN</u> Chung-hyuk SHIN
Date: <u>January</u> , <u>13</u> , 1999	Signature of Inventor: <u>Jung-ki KIM</u> Jung-ki KIM